

**PRODUCT DISCONTINUATION NOTICE - LAST TIME BUY EXPIRES MAY 6, 2017**

**GENERAL DESCRIPTION**

The 843022 is a Gigabit Ethernet Clock Generator and a member of the HiPerClocks™ family of high performance devices from IDT. The 843022 uses a 25MHz crystal to synthesize 125MHz or 62.5MHz. The 843022 has excellent phase jitter performance, over the 1.875MHz – 20MHz integration range. The 843022 is packaged in a small 8-pin TSSOP, making it ideal for use in systems with limited board space.

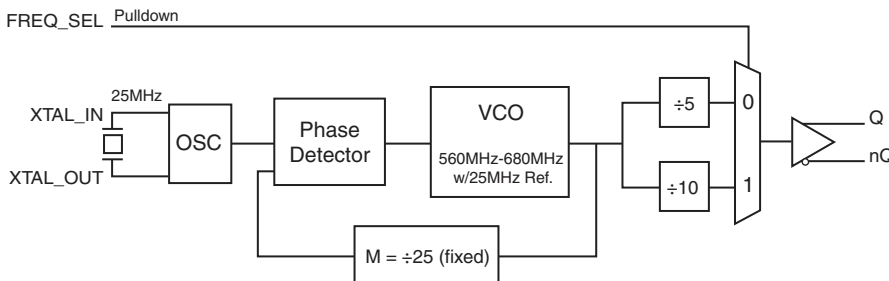
**FEATURES**

- One differential 3.3V LVPECL output
  - Crystal oscillator interface designed for 25MHz, 18pF parallel resonant crystal
  - Output frequencies: 125MHz or 62.5MHz (selectable)
  - RMS phase jitter @ 125MHz, using a 25MHz crystal (1.875MHz - 20MHz): 0.39ps (typical)
- | Offset       | Noise Power   |
|--------------|---------------|
| 100Hz .....  | -96.5 dBc/Hz  |
| 1kHz .....   | -122.5 dBc/Hz |
| 10kHz .....  | -132.1 dBc/Hz |
| 100kHz ..... | -131.5 dBc/Hz |
- 3.3V operating supply
  - 0°C to 70°C ambient operating temperature
  - Industrial temperature information available upon request
  - Available in lead-free (RoHS 6) package

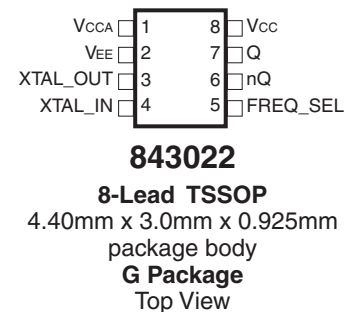
**FUNCTION TABLE**

Inputs	Output Frequencies (with a 25MHz crystal)
FREQ_SEL	
0	125MHz
1	62.5MHz

**BLOCK DIAGRAM**



**PIN ASSIGNMENT**



**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1	V <sub>CCA</sub>	Power		Analog supply pin.
2	V <sub>EE</sub>	Power		Negative supply pin.
3, 4	XTAL_OUT, XTAL_IN	Input		Crystal oscillator interface. XTAL_in is the input, XTAL_OUT is the output.
5	FREQ_SEL	Input	Pulldown	Frequency select pin. LVCMOS/LVTTL interface levels.
6, 7	nQ, Q	Output		Differential clock outputs. LVPECL interface levels.
8	V <sub>CC</sub>	Power		Core supply pin.

NOTE: *Pulldown* refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{CC}$	4.6V
Inputs, $V_I$	-0.5V to $V_{CC} + 0.5V$
Outputs, $I_O$	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, $\theta_{JA}$	101.7°C/W (0 mps)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 3A. POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{CCA}$	Analog Supply Voltage		$V_{CC} - 0.1$	3.3	$V_{CC}$	V
$I_{CCA}$	Analog Supply Current				10	mA
$I_{EE}$	Power Supply Current				90	mA

**TABLE 3B. LVCMOS/LVTTL DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage		2		$V_{CC} + 0.3$	V
$V_{IL}$	Input Low Voltage		-0.3		0.8	V
$I_{IH}$	Input High Current	FREQ_SEL $V_{CC} = V_{IN} = 3.465V$			150	$\mu A$
$I_{IL}$	Input Low Current	FREQ_SEL $V_{CC} = 3.465V, V_{IN} = 0V$	-5			$\mu A$

**TABLE 3C. LVPECL DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OH}$	Output High Voltage; NOTE 1		$V_{CC} - 1.4$		$V_{CC} - 0.9$	V
$V_{OL}$	Output Low Voltage; NOTE 1		$V_{CC} - 2.0$		$V_{CC} - 1.7$	V
$V_{SWING}$	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

**TABLE 4. CRYSTAL CHARACTERISTICS**

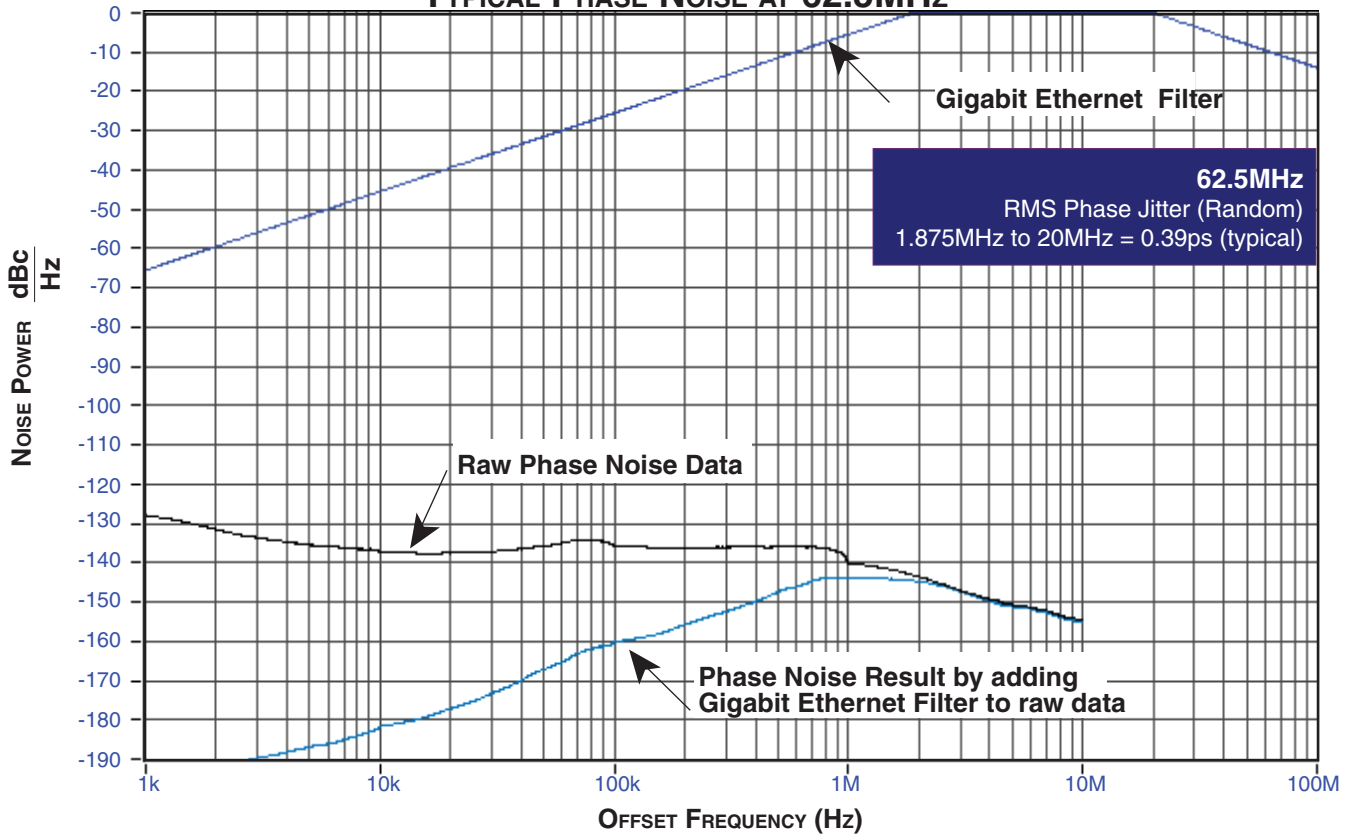
Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency			25		MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Drive Level				1	mW

**TABLE 5. AC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

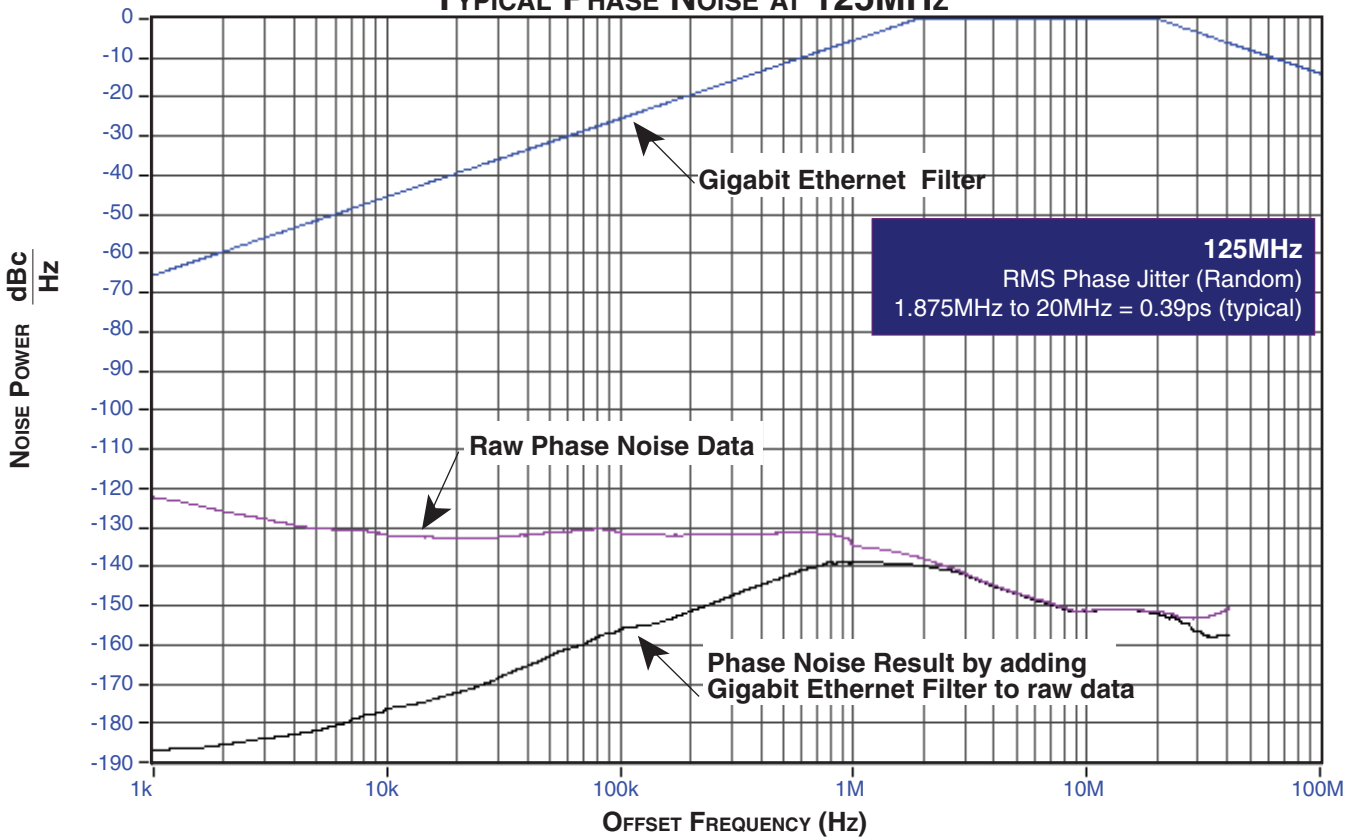
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{OUT}$	Output Frequency	F_SEL = 0		125		MHz
		F_SEL = 1		62.5		MHz
$\sigma_{jit}(\emptyset)$	RMS Phase Jitter; NOTE 1	125MHz, Integration Range: 1.875MHz - 20MHz		0.39		ps
		62.5MHz, Integration Range: 1.875MHz - 20MHz		0.39		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	300		600	ps
odc	Output Duty Cycle		48		52	%

NOTE 1: Please refer to the Phase Noise Plot.

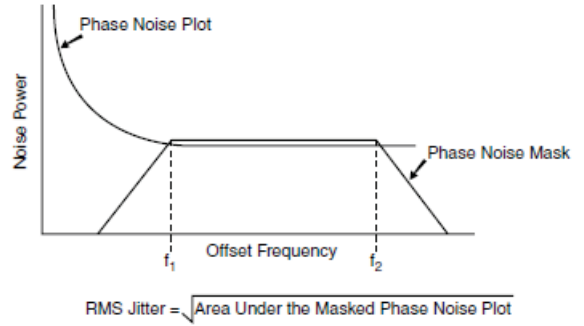
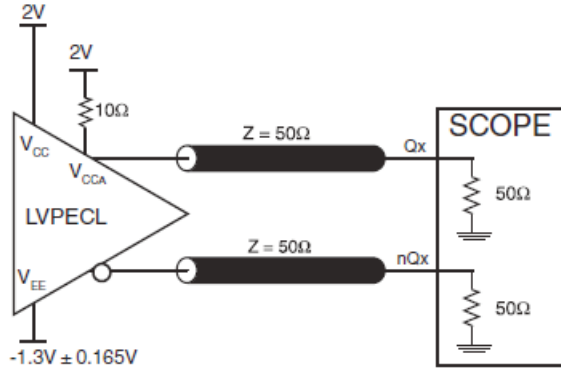
TYPICAL PHASE NOISE AT 62.5MHz



TYPICAL PHASE NOISE AT 125MHz

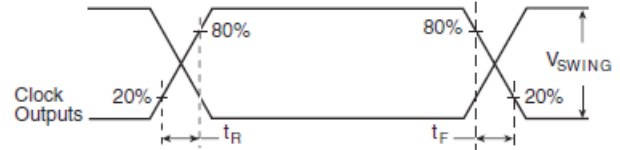
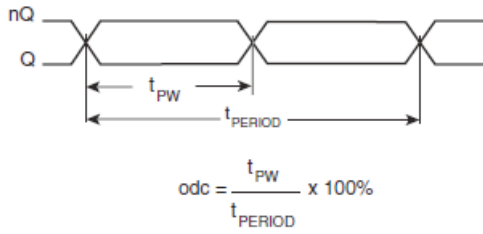


## PARAMETER MEASUREMENT INFORMATION



3.3V OUTPUT LOAD AC TEST CIRCUIT

RMS PHASE JITTER



OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

OUTPUT RISE/FALL TIME

## APPLICATION INFORMATION

### POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The 843022 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{CC}$  and  $V_{CCA}$  should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 1* illustrates how a  $10\Omega$  resistor along with a  $10\mu\text{F}$  and a  $.01\mu\text{F}$  bypass capacitor should be connected to each  $V_{CCA}$  pin.

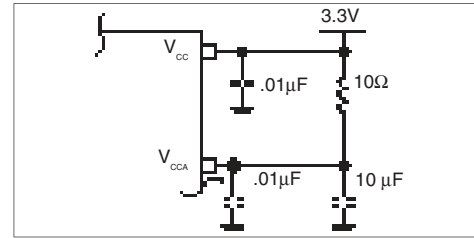


FIGURE 1. POWER SUPPLY FILTERING

### CRYSTAL INPUT INTERFACE

The 843022 has been characterized with  $18\text{pF}$  parallel resonant crystals. The capacitor values,  $C1$  and  $C2$ , shown in *Figure 2* below were determined using a  $25\text{MHz}$ ,  $18\text{pF}$  parallel

resonant crystal and were chosen to minimize the ppm error. The optimum  $C1$  and  $C2$  values can be slightly adjusted for different board layouts.

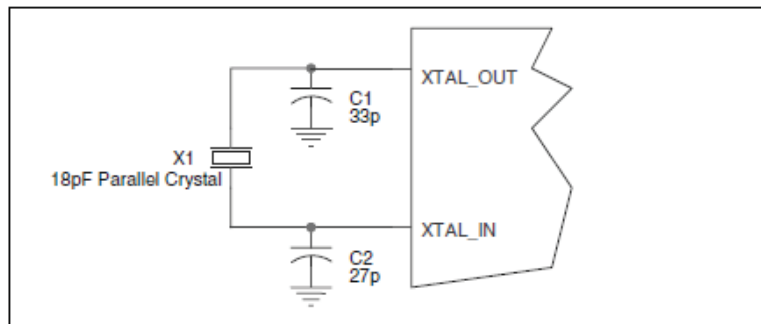
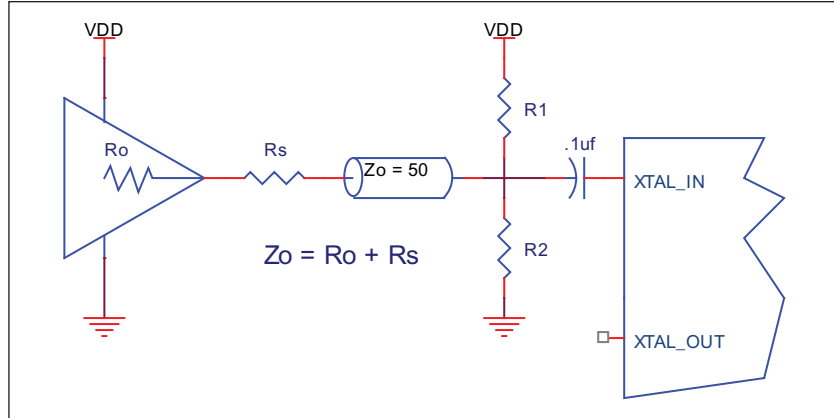


Figure 2. CRYSTAL INPUT INTERFACE

**LVC MOS TO XTAL INTERFACE**

The XTAL\_IN input can accept a single-ended LVC MOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 3*. The XTAL\_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVC MOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output

impedance of the driver ( $R_o$ ) plus the series resistance ( $R_s$ ) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First,  $R_1$  and  $R_2$  in parallel should equal the transmission line impedance. For most 50Ω applications,  $R_1$  and  $R_2$  can be 100Ω. This can also be accomplished by removing  $R_1$  and making  $R_2$  50Ω.



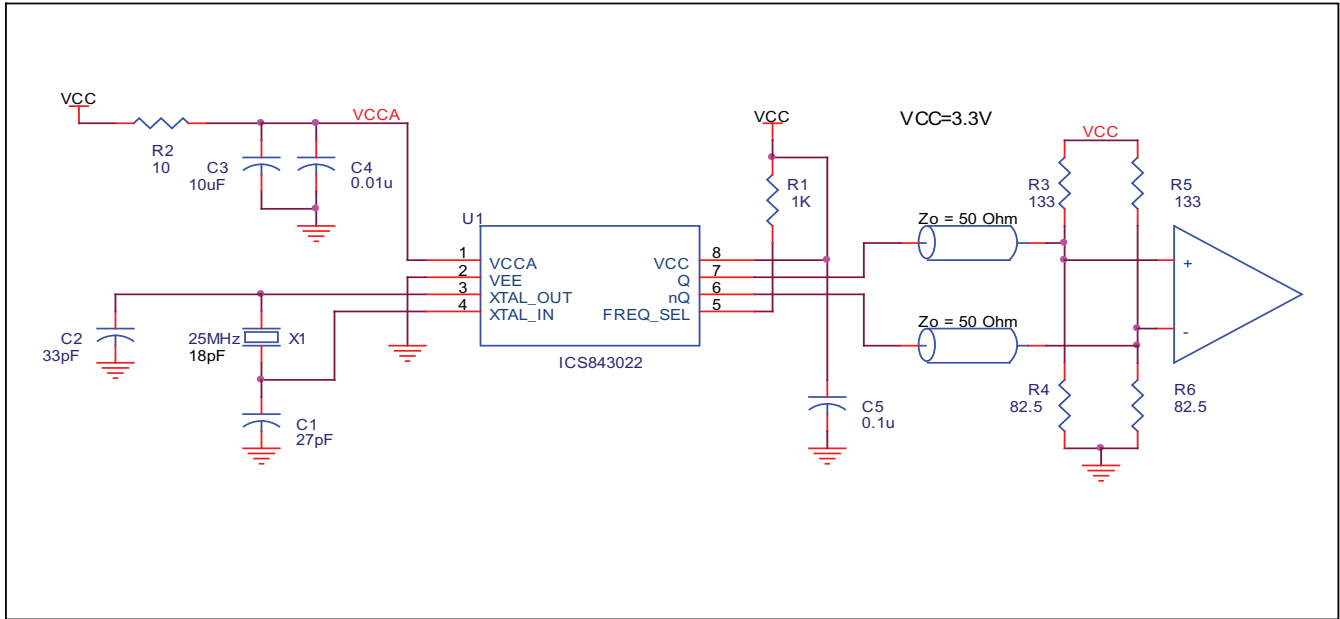
**FIGURE 3. GENERAL DIAGRAM FOR LVC MOS DRIVER TO XTAL INPUT INTERFACE**



**APPLICATION SCHEMATIC**

Figure 4A shows a schematic example of the 843022. An example of LVEPCL termination is shown in this schematic. Additional LVPECL termination approaches are shown in the LVPECL Termination Application Note. In this example, an 18pF parallel resonant 25MHz

crystal is used for generating 125MHz output frequency. The C1 = 27pF and C2 = 33pF are recommended for frequency accuracy. For different board layout, the C1 and C2 values may be slightly adjusted for optimizing frequency accuracy.

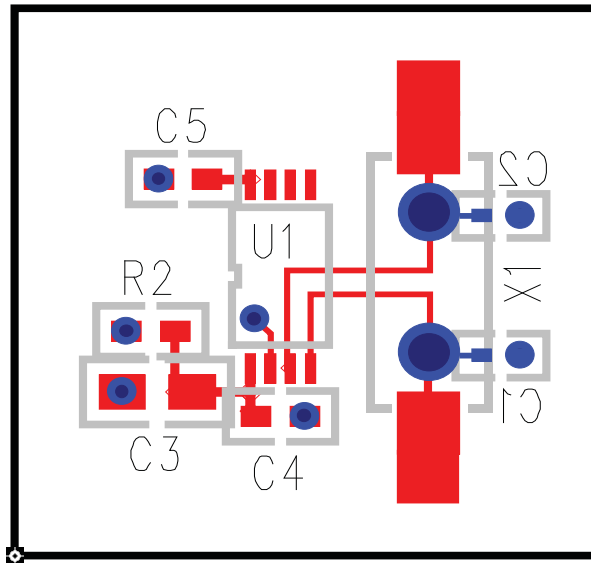


**FIGURE 4A. 843022 SCHEMATIC EXAMPLE**

**PC BOARD LAYOUT EXAMPLE**

Figure 4B shows an example of P.C. board layout. The crystal X1 footprint in this example allows either surface mount (HC49S) or through hole (HC49) package. C3 is 0805. C1 and C2 are 0402.

Other resistors and capacitors are 0603. This layout assumes that the board has clean analog power and ground planes.



**FIGURE 4B. 843022 PC BOARD LAYOUT EXAMPLE**

## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the 843022. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the 843022 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 3.465V * 90mA = 311.85mW$
- Power (outputs)<sub>MAX</sub> = **30mW/Loaded Output pair**

**Total Power**<sub>MAX</sub> (3.465V, with all outputs switching) =  $311.85mW + 30mW = 341.85mW$

### 2. Junction Temperature.

Junction temperature, T<sub>j</sub>, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T<sub>j</sub> is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

T<sub>j</sub> = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

Pd<sub>total</sub> = Total Device Power Dissipation (example calculation is in section 1 above)

T<sub>A</sub> = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 1 meter per second and a multi-layer board, the appropriate value is 90.5°C/W per Table 6 below.

Therefore, T<sub>j</sub> for an ambient temperature of 70°C with all outputs switching is:

$70^\circ C + 0.342W * 90.5^\circ C/W = 101^\circ C$ . This is well below the limit of 125°C.

This calculation is only an example. T<sub>j</sub> will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 6. THERMAL RESISTANCE  $\theta_{JA}$  FOR 8-PIN TSSOP, FORCED CONVECTION**

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 5.

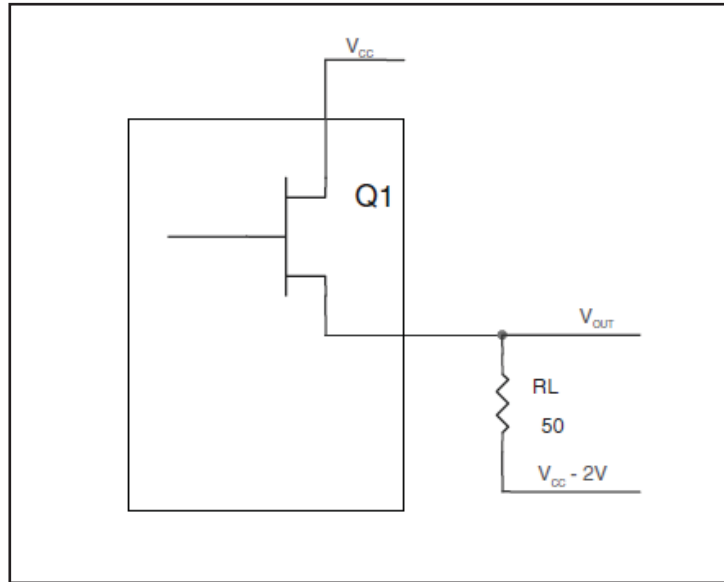


FIGURE 5. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V<sub>CC</sub> - 2V.

- For logic high, V<sub>OUT</sub> = V<sub>OH\_MAX</sub> = V<sub>CC\_MAX</sub> - 0.9V

$$(V_{CC\_MAX} - V_{OH\_MAX}) = 0.9V$$

- For logic low, V<sub>OUT</sub> = V<sub>OL\_MAX</sub> = V<sub>CC\_MAX</sub> - 1.7V

$$(V_{CC\_MAX} - V_{OL\_MAX}) = 1.7V$$

Pd<sub>H</sub> is power dissipation when the output drives high.

Pd<sub>L</sub> is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

$$\text{Total Power Dissipation per output pair} = Pd\_H + Pd\_L = 30mW$$

## RELIABILITY INFORMATION

TABLE 7.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD TSSOP

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

### TRANSISTOR COUNT

The transistor count for 843022 is: 1928

PACKAGE OUTLINE - G SUFFIX FOR 8 LEAD TSSOP

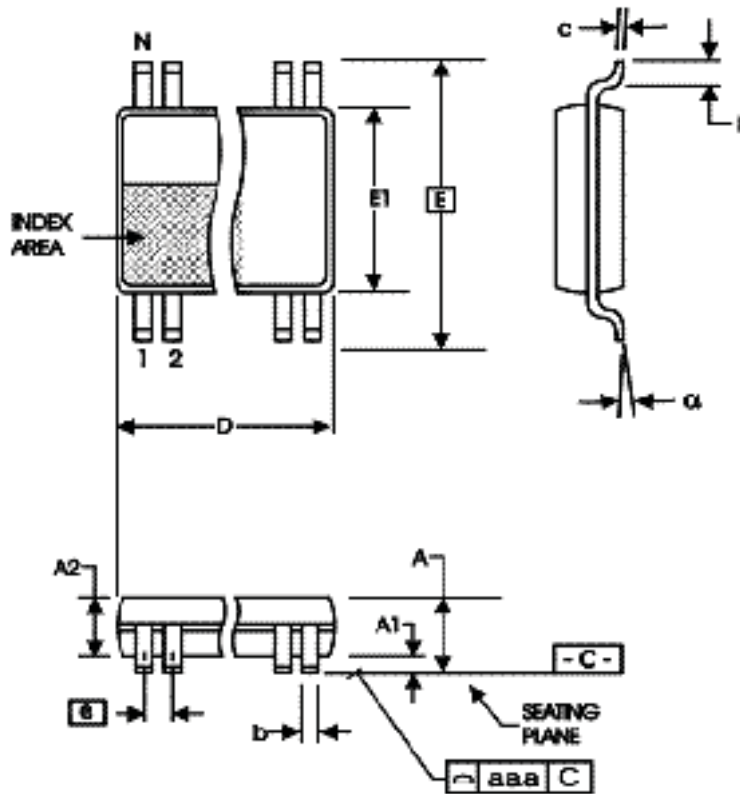


TABLE 8. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	8	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	2.90	3.10
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
$\alpha$	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

**TABLE 9. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
843022AGLF	022AL	8 lead "Lead-Free" TSSOP	Tube	0°C to 70°C
843022AGLFT	022AL	8 lead "Lead-Free" TSSOP	Tape & Reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

**REVISION HISTORY SHEET**

<b>Rev</b>	<b>Table</b>	<b>Page</b>	<b>Description of Change</b>	<b>Date</b>
A	T9	14	Ordering Information - removed leaded devices. Updated data sheet format.	11/16/15
A			Product Discontinuation Notice - Last time buy expires May 6, 2017. PDN CQ-16-01	5/26/16





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